



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20190509001.1
Transfer of select DLM devices from GFAB to FFAB Wafer Fab site
Change Notification / Sample Request

Date: May 13, 2019
To: Newark/Farnell PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Team (PCN_ww_admin_team@list.ti.com). For sample requests or sample related questions, contact the TI Samples Team at pcn_sr_team@list.ti.com.

PCN Team
SC Business Services



20190509001.1
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
DS3695AMX/NOPB	null
DS8921AM/NOPB	null
DS8921AMX/NOPB	null
DS8921ATM/NOPB	null
DS8921M/NOPB	null
DS8921MX/NOPB	null
LM9061M/NOPB	null
DS3695AM/NOPB	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20190509001.1		PCN Date:	May 13, 2019	
Title:	Transfer of select DLM devices from GFAB to FFAB Wafer Fab site				
Customer Contact:	PCN Manager		Dept:	Quality Services	
Proposed 1st Ship Date:	Aug 13, 2019	Estimated Sample Availability:	Date provided at sample request.		
Change Type:					
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Assembly Materials
<input type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification	<input type="checkbox"/>	Mechanical Specification
<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material	<input type="checkbox"/>	Wafer Bump Process
<input checked="" type="checkbox"/>	Wafer Fab Site	<input checked="" type="checkbox"/>	Wafer Fab Materials	<input type="checkbox"/>	Wafer Fab Process
		<input type="checkbox"/>	Part number change		
PCN Details					
Description of Change:					
This change notification is to announce the transfer of select DLM devices from GFAB to the FFAB (FR-BIP-1) Wafer Fab site for the selected devices listed in the "Product Affected" section.					
Current Fab Site			New Fab Site		
Current Fab Site	Process	Wafer Diameter	New Fab Site	Process	Wafer Diameter
GFAB6	DLM	150 mm	FFAB	DLM	200 mm
Qual details are provided in the Qual Data Section.					
Reason for Change:					
Greenock, Scotland (GFAB) Wafer Fab site closure					
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):					
None					
Changes to product identification resulting from this PCN:					
Current					
Chip Site	Chip Site Origin (20L)	Chip Site Country Code (21L)	Chip Site City		
GFAB6	GF6	GBR	Greenock		
New Fab Site					
Chip Site	Chip Site Origin (20L)	Chip Site Country Code (21L)	Chip Site City		
FR-BIP-1	TID	DEU	Freising		
Sample product shipping label (not actual product label)					
 MADE IN: Malaysia 2DC: 2G: MSL 2 / 260C / 1 YEAR SEAL DT MSL 1 / 235C / UNLIM 03/29/04 OPT: ITEM: 39 LBL: 5A (L)T0:1750		 G4	(1P) SN74LS07NSR (Q) 2000 (D) 0336 (31T) LOT: 3959047MLA (4W) TKY (1T) 7523483S12 (P) (2P) REV: (V) 0033317 (20L) CSO: SHE (21L) CCO: USA (22L) ASO: MLA (23L) ACO: MYS		
Product Affected Group:					
DS36277TMX/NOPB	DS8921ATM/NOPB	LM317LITPX/NOPB	LM9071S/NOPB		
DS3695AM/NOPB	DS8921M/NOPB	LM614 MDC	LM9071SX/NOPB		
DS3695AMX/NOPB	DS8921MX/NOPB	LM9061M/NOPB	LM9071SX/S5000467		
DS8921AM/NOPB	LM317LITP/NOPB	LM9061MX/NOPB	LMB1024MX-1/E7001820		
DS8921AMX/NOPB					

Qualification Report

Approve Date 7-May-2019

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: LM9061QDRQ1	QBS Reference: LM2576HVT-5.0/NOPB
HAST	Bias ed HAST, 130C/85%RH	96 Hours	3/231/0	-
AC	Autoclave 121C	96 Hours	3/231/0	-
TC	Temperature Cycle, -65/150C	500 Cycles	3/231/0	-
HTSL	High Temp. Storage Bake, 150C	1000 Hours	3/231/0	-
HTOL	Life Test, 125C	1000 Hours	1/77/0	3/231/0
ELFR	Early Life Failure Rate, 125C	48 Hours	2/1600/0	3/2400/0
HBM	ESD - HBM	2500 V	3/9/0	-
CDM	ESD - CDM	1500 V	3/9/0	-
LU	Latch-up	(per JESD78)	3/18/0	-
ED	Electrical Distributions	Per Datasheet Parameters	3/90/0	-

- Qual Device LM9061QDRQ1 is qualified at LEVEL3-260C

- QBS: Qual By Similarity

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Bias ed HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free (SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below, or you can contact your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
WW PCN Team	PCN_ww_admin_team@list.ti.com